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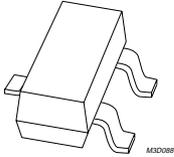
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Kind regards,

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BSH108

N-channel enhancement mode field-effect transistor

Rev. 02 — 25 October 2000

Product specification

1. Description

N-channel enhancement mode field-effect transistor in a plastic package using TrenchMOS™¹ technology.

Product availability:
BSH108 in SOT23.

2. Features

- TrenchMOS™ technology
- Very fast switching
- Logic level compatible
- Subminiature surface mount package.

3. Applications

- Battery management
- High speed switch
- Low power DC to DC converter.

4. Pinning information

Table 1: Pinning - SOT23, simplified outline and symbol

Pin	Description	Simplified outline	Symbol
1	gate (g)	<p>Top view MSB003</p> <p>SOT23</p>	<p>MBB076</p>
2	source (s)		
3	drain (d)		

1. TrenchMOS is a trademark of Royal Philips Electronics.



5. Quick reference data

Table 2: Quick reference data

Symbol	Parameter	Conditions	Typ	Max	Unit
V_{DS}	drain-source voltage (DC)	$T_j = 25$ to 150 °C	–	30	V
I_D	drain current (DC)	$T_{sp} = 25$ °C; $V_{GS} = 5$ V	–	1.9	A
P_{tot}	total power dissipation	$T_{sp} = 25$ °C	–	0.83	W
T_j	junction temperature		–	150	°C
R_{DSon}	drain-source on-state resistance	$V_{GS} = 10$ V; $I_D = 1$ A	77	120	mΩ
		$V_{GS} = 5$ V; $I_D = 1$ A	102	140	mΩ

6. Limiting values

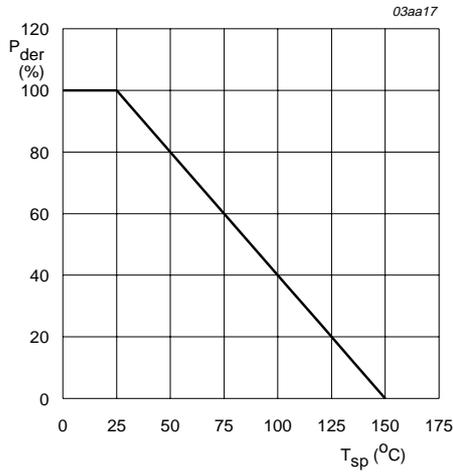
Table 3: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage (DC)	$T_j = 25$ to 150 °C	–	30	V
V_{DGR}	drain-gate voltage (DC)	$T_j = 25$ to 150 °C; $R_{GS} = 20$ kΩ	–	30	V
V_{GS}	gate-source voltage (DC)		–	±20	V
I_D	drain current (DC)	$T_{sp} = 25$ °C; $V_{GS} = 5$ V; Figure 2 and 3	–	1.9	A
		$T_{sp} = 100$ °C; $V_{GS} = 5$ V; Figure 2	–	1.2	A
I_{DM}	peak drain current	$T_{sp} = 25$ °C; pulsed; $t_p \leq 10$ μs; Figure 3	–	7.5	A
P_{tot}	total power dissipation	$T_{sp} = 25$ °C; Figure 1	–	0.83	W
T_{stg}	storage temperature		–65	+150	°C
T_j	operating junction temperature		–65	+150	°C

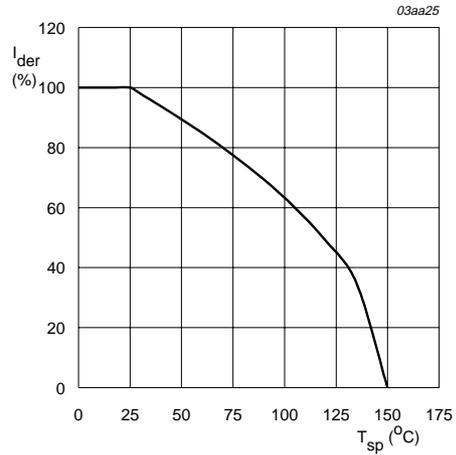
Source-drain diode

I_S	source (diode forward) current (DC)	$T_{sp} = 25$ °C	–	0.83	A
I_{SM}	peak source (diode forward) current	$T_{sp} = 25$ °C; pulsed; $t_p \leq 10$ μs	–	3.3	A



$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$$

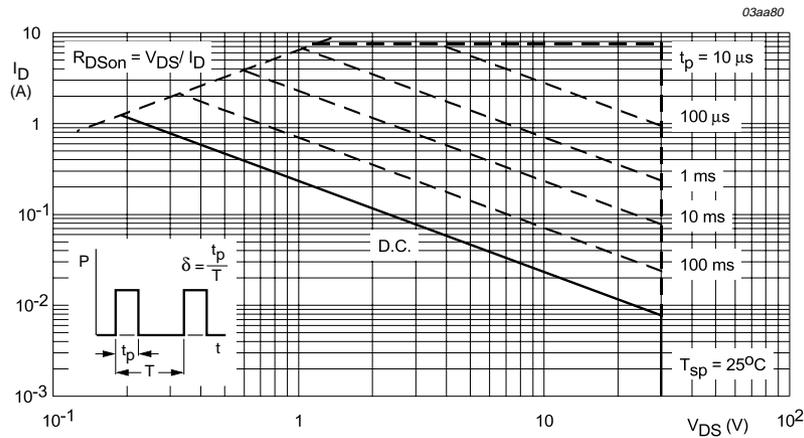
Fig 1. Normalized total power dissipation as a function of solder point temperature.



$V_{GS} \geq 5\text{ V}$

$$I_{der} = \frac{I_D}{I_{D(25^{\circ}C)}} \times 100\%$$

Fig 2. Normalized continuous drain current as a function of solder point temperature.



$T_{sp} = 25^{\circ}C$; I_{DM} is single pulse.

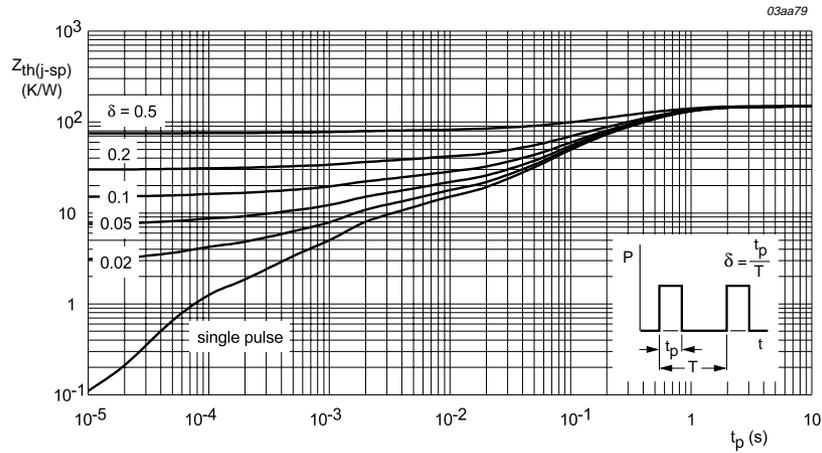
Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage.

7. Thermal characteristics

Table 4: Thermal characteristics

Symbol	Parameter	Conditions	Value	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point	mounted on a metal clad substrate; Figure 4	150	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	mounted on a printed circuit board; minimum footprint	350	K/W

7.1 Transient thermal impedance



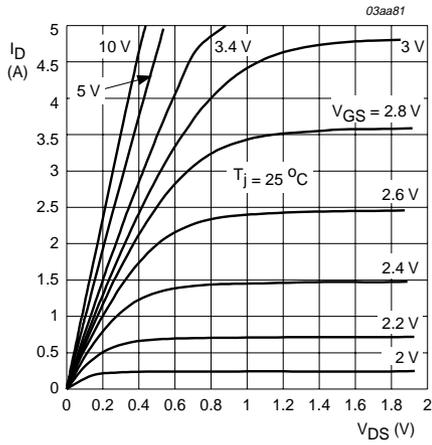
Mounted on a metal clad substrate.

Fig 4. Transient thermal impedance from junction to solder point as a function of pulse duration.

8. Characteristics

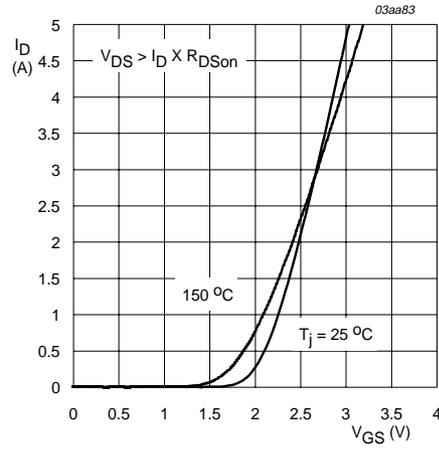
Table 5: Characteristics
 $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 10\text{ }\mu\text{A}$; $V_{GS} = 0\text{ V}$ $T_j = 25\text{ }^\circ\text{C}$	30	40	–	V
		$T_j = -55\text{ }^\circ\text{C}$	27	–	–	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1\text{ mA}$; $V_{DS} = V_{GS}$; Figure 9 $T_j = 25\text{ }^\circ\text{C}$	1	1.5	2	V
		$T_j = 150\text{ }^\circ\text{C}$	0.5	–	–	V
		$T_j = -55\text{ }^\circ\text{C}$	–	–	3.2	V
I_{DSS}	drain-source leakage current	$V_{DS} = 24\text{ V}$; $V_{GS} = 0\text{ V}$ $T_j = 25\text{ }^\circ\text{C}$	–	0.01	1.0	μA
		$T_j = 150\text{ }^\circ\text{C}$	–	–	10	μA
I_{GSS}	gate-source leakage current	$V_{GS} = \pm 10\text{ V}$; $V_{DS} = 0\text{ V}$	–	10	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}$; $I_D = 1\text{ A}$; Figure 7 and 8 $T_j = 25\text{ }^\circ\text{C}$	–	77	120	m Ω
		$V_{GS} = 5\text{ V}$; $I_D = 1\text{ A}$; Figure 7 and 8 $T_j = 25\text{ }^\circ\text{C}$	–	102	140	m Ω
		$T_j = 150\text{ }^\circ\text{C}$	–	170	240	m Ω
Dynamic characteristics						
g_{fs}	forward transconductance	$V_{DS} = 10\text{ V}$; $I_D = 1\text{ A}$; Figure 11	2	4.5	–	S
$Q_{g(tot)}$	total gate charge	$V_{DD} = 15\text{ V}$; $V_{GS} = 10\text{ V}$; $I_D = 5\text{ A}$; Figure 14	–	6.4	10	nC
Q_{gs}	gate-source charge		–	0.5	–	nC
Q_{gd}	gate-drain (Miller) charge		–	1.3	–	nC
C_{iss}	input capacitance	$V_{GS} = 0\text{ V}$; $V_{DS} = 10\text{ V}$; $f = 1\text{ MHz}$; Figure 12	–	190	–	pF
C_{oss}	output capacitance		–	70	–	pF
C_{rss}	reverse transfer capacitance		–	50	–	pF
$t_{d(on)}$	turn-on delay time	$V_{DD} = 10\text{ V}$; $R_L = 10\text{ }\Omega$; $V_{GS} = 10\text{ V}$; $R_G = 6\text{ }\Omega$	–	3	–	ns
t_r	rise time		–	8	–	ns
$t_{d(off)}$	turn-off delay time		–	15	–	ns
t_f	fall time		–	26	–	ns
Source-drain diode						
V_{SD}	source-drain (diode forward) voltage	$I_S = 0.83\text{ A}$; $V_{GS} = 0\text{ V}$; Figure 13	–	0.8	1.2	V
t_{rr}	reverse recovery time	$I_S = 1\text{ A}$; $dI_S/dt = -100\text{ A}/\mu\text{s}$; $V_{GS} = 0\text{ V}$; $V_{DS} = 25\text{ V}$	–	25	–	ns
Q_r	recovered charge		–	20	–	nC



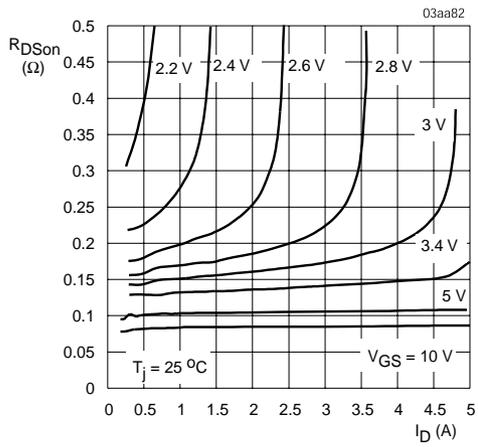
$T_j = 25\text{ }^\circ\text{C}$

Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values.



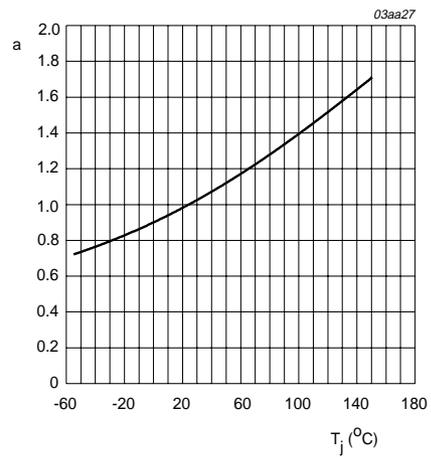
$T_j = 25\text{ }^\circ\text{C}$ and $150\text{ }^\circ\text{C}$; $V_{DS} > I_D \times R_{DSon}$

Fig 6. Transfer characteristics: drain current as a function of gate-source voltage; typical values.



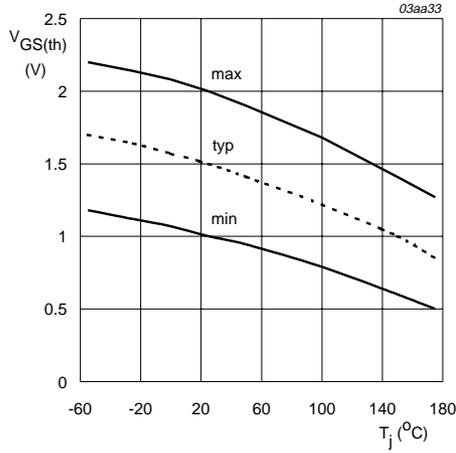
$T_j = 25\text{ }^\circ\text{C}$

Fig 7. Drain-source on-state resistance as a function of drain current; typical values.



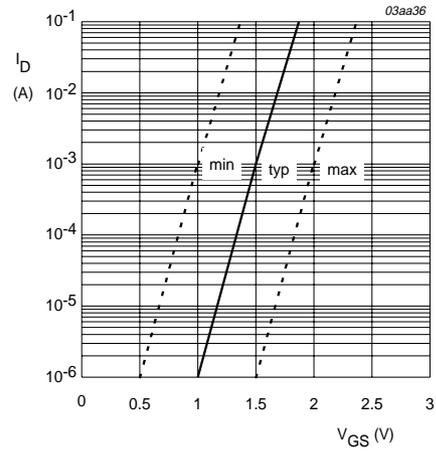
$$a = \frac{R_{DSon}}{R_{DSon(25^\circ\text{C})}}$$

Fig 8. Normalized drain-source on-state resistance factor as a function of junction temperature.



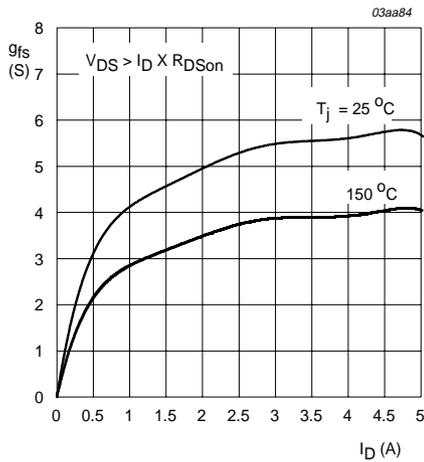
$I_D = 1 \text{ mA}; V_{DS} = V_{GS}$

Fig 9. Gate-source threshold voltage as a function of junction temperature.



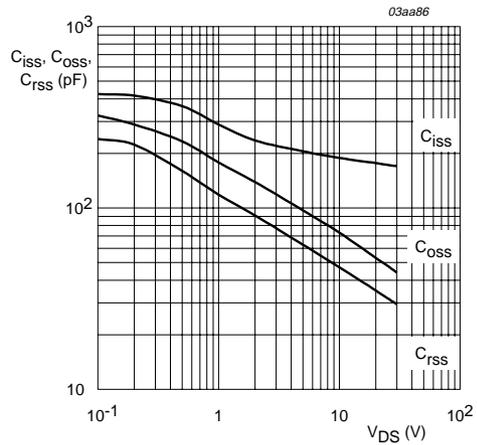
$T_j = 25 \text{ }^{\circ}C; V_{DS} = 5 \text{ V}$

Fig 10. Sub-threshold drain current as a function of gate-source voltage.



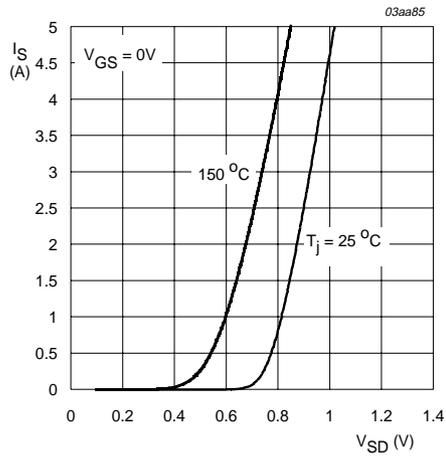
$T_j = 25 \text{ }^{\circ}C$ and $150 \text{ }^{\circ}C; V_{DS} > I_D \times R_{DSon}$

Fig 11. Forward transconductance as a function of drain current; typical values.



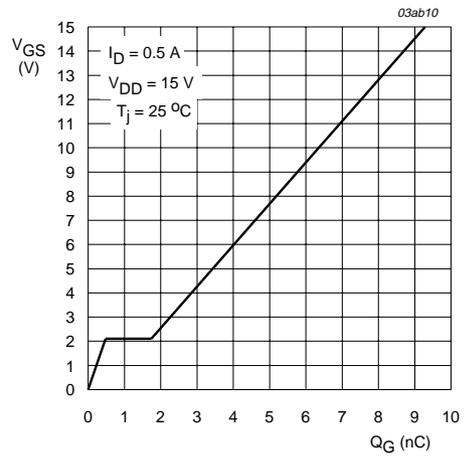
$V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$

Fig 12. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values.



$T_j = 25^\circ C$ and $150^\circ C$; $V_{GS} = 0V$

Fig 13. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values.



$I_D = 0.5A$; $V_{DD} = 15V$; $T_j = 25^\circ C$

Fig 14. Gate-source voltage as a function of gate charge; typical values.

9. Package outline

Plastic surface mounted package; 3 leads

SOT23

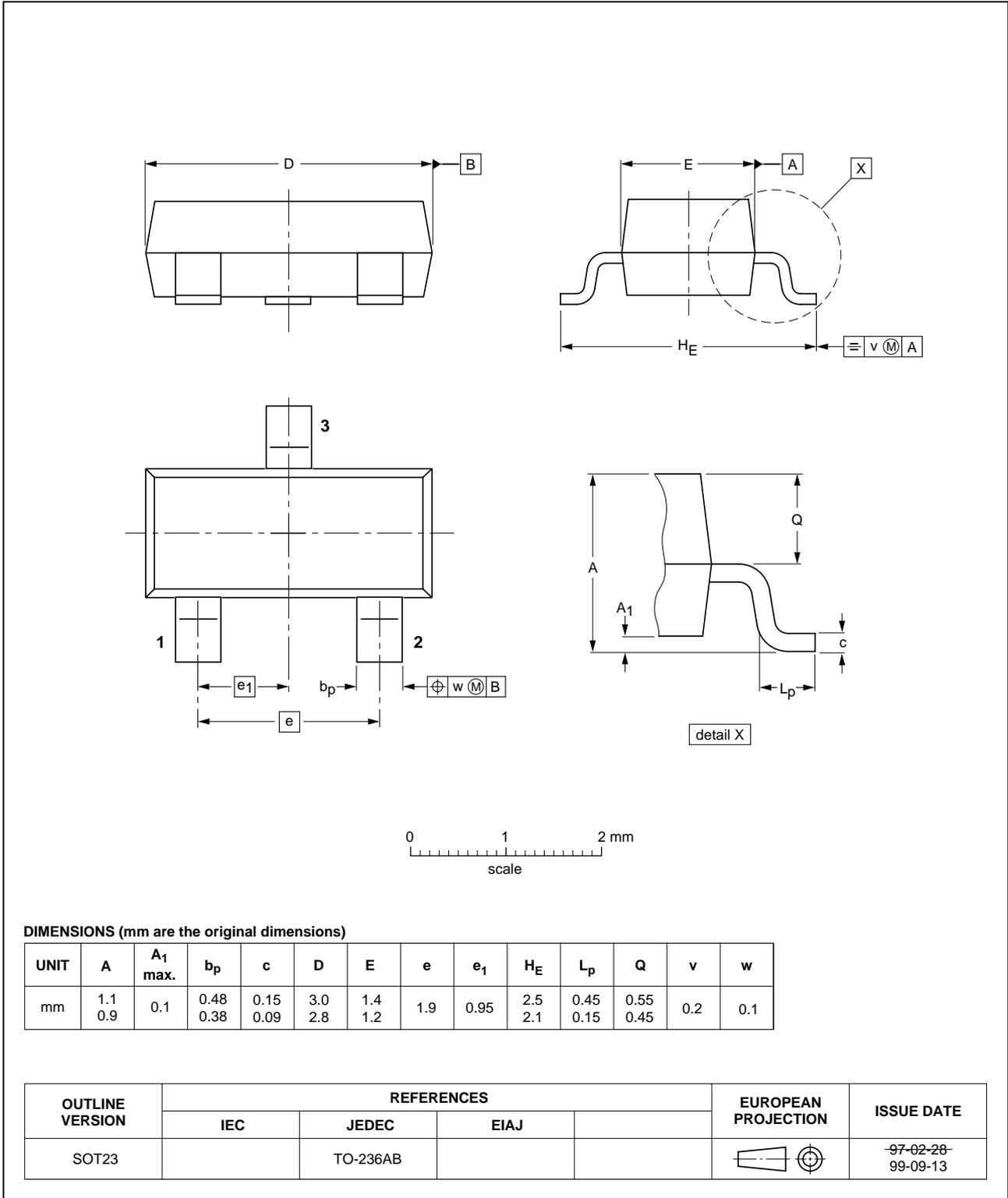


Fig 15. SOT23.

10. Revision history

Table 6: Revision history

Rev	Date	CPCN	Description
02	20001025	-	Product specification; second version; supersedes Rev.01 of 20000906. Correction to diode I_S ; see Table 3 "Limiting values"
01	20000906	-	Product specification.

11. Data sheet status

Datasheet status	Product status	Definition ^[1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued data sheet before initiating or completing a design.

12. Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Belarus: Tel. +375 17 220 0733, Fax. +375 17 220 0773

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Brazil: see South America

Bulgaria: Tel. +359 268 9211, Fax. +359 268 9102

Canada: Tel. +1 800 234 7381

China/Hong Kong: Tel. +852 2 319 7888, Fax. +852 2 319 7700

Colombia: see South America

Czech Republic: see Austria

Denmark: Tel. +45 3 288 2636, Fax. +45 3 157 0044

Finland: Tel. +358 961 5800, Fax. +358 96 158 0920

France: Tel. +33 14 099 6161, Fax. +33 14 099 6427

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Hungary: see Austria

India: Tel. +91 22 493 8541, Fax. +91 22 493 8722

Indonesia: see Singapore

Ireland: Tel. +353 17 64 0000, Fax. +353 17 64 0200

Israel: Tel. +972 36 45 0444, Fax. +972 36 49 1007

Italy: Tel. +39 039 203 6838, Fax. +39 039 203 6800

Japan: Tel. +81 33 740 5130, Fax. +81 3 3740 5057

Korea: Tel. +82 27 09 1412, Fax. +82 27 09 1415

Malaysia: Tel. +60 37 50 5214, Fax. +60 37 57 4880

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For all other countries apply to: Philips Semiconductors,
Marketing Communications,
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Netherlands: Tel. +31 40 278 2785, Fax. +31 40 278 8399

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Poland: Tel. +48 22 5710 000, Fax. +48 22 5710 001

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Turkey: Tel. +90 216 522 1500, Fax. +90 216 522 1813

Ukraine: Tel. +380 44 264 2776, Fax. +380 44 268 0461

United Kingdom: Tel. +44 208 730 5000, Fax. +44 208 754 8421

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Uruguay: see South America

Vietnam: see Singapore

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